

1

2

3

4

5

6

Layer

Name

Material

Thickness

Constant

Board Layer Stack

1

Top Overlay

2

Top Solder

Solder Resist

0.40mil

3.5

3

Top Layer

Copper

1.40mil

4

Dielectricl

FR-4

59.20mil

4.8

5

Bottom Layer

Copper

1.40mil

6

Bottom Solder

Solder Resist

0.40mil

3.5

7

Bottom Overlay

Symbol

Quantity

Finished Hole Size

Plated

Hole Type

Drill Layer Pair

Hole Tolerance

⊗

1

70.08mil (1.780mm)

NPTH

Round

Top Layer - Bottom Layer

⊗

14

7.87mil (0.200mm)

PTH

Round

Top Layer - Bottom Layer

⊗

125

12.00mil (0.305mm)

PTH

Round

Top Layer - Bottom Layer

○

28

26.00mil (0.711mm)

PTH

Round

Top Layer - Bottom Layer

▽

20

40.00mil (1.016mm)

PTH

Round

Top Layer - Bottom Layer

□

49

40.16mil (1.020mm)

PTH

Round

Top Layer - Bottom Layer

◇

12

55.00mil (1.397mm)

PTH

Round

Top Layer - Bottom Layer

249 Total

Score line to separate motherboard from daughtercard post-assembly. Seperate daughtercard post-assembly for individual packaging of motherboard and daughtercard.

2720.00mil

2300.00mil

1000.00mil

720.00mil

2000.00mil

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: MSA004

REV: A

SUN REV: Not In VersionControl

Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

LAYER NAME = ~~BOOSTXL-460~~ BoostXL-460

TID #: N/A

PLOT NAME = Fabrication Drawing

GENERATED : 2/7/2017 11:52:25 AM

TEXAS INSTRUMENTS

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

FR-408

☒ FR-4 High Tg

☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES

PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER

SOLDER RESIST COLOR: ☐ GREEN ☒ OTHER RED

☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG

☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE

☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3

☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.

PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES

BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

TEXASINSTRUMENTS

PROJECT TITLE:  
BOOSTXL-PGA460

DESIGNED FOR:  
Public Release

FILE NAME:  
MSA004A\_PCB.PcbDoc

ENGINEER:  
A. WHITEHEAD

LAYOUT BY:  
A. WHITEHEAD

SCALE: 1.00

ALTUM DESIGNER VERSION:  
16.0.1.132